



(一社)日本半導体製造装置協会

東京都千代田区六番町 3
番地六番町SKビル6F
Web <http://www.seaj.or.jp>

2019年1月度 販売高 (SEAJ 速報値) 日本製半導体製造装置 (3ヶ月平均)

注意: データは3ヵ月移動平均です。

次回予定: SEAJ 2月度販売高 3/19 16:00

SEAJ ホームページアップ予定

日本製 半導体製造装置 2019年1月度の販売高は 164,993 百万円

東京 2019年2月20日 - 日本半導体製造装置協会が20日に発表した1月度の半導体製造装置速報値によると日本製装置(輸出を含む)の販売高は、前月比 **1.8%**減(2018年12月度確定値は **168,098** 百万円)、前年同月比 **3.3%**増(2018年1月度は **159,771** 百万円)の **164,993** 百万円だった。

単位: 百万円

	販売 (3ヶ月平均)	前月比 (%)	前年比 (%)
2018/8	181,450	-3.9%	11.9%
2018/9	214,089	18.0%	34.7%
2018/10	200,113	-6.5%	29.5%
2018/11	204,672	2.3%	33.4%
2018/12(確定値)	168,098	-17.9%	8.1%
2019/1(暫定値)	164,993	-1.8%	3.3%

本データは速報値(3ヶ月移動平均)です。確定値とは多少差異が生じる場合がありますのでご利用に際してはご注意ください。

なおSEMIは北米製の半導体製造装置の Billings の速報を公表しています。

<http://www.semi.org/en/MarketInfo/billings>

お問い合わせ先 :

事務局 広報部長 小林 章秀(こばやし あきひで)

Web <http://www.seaj.or.jp> E-mail akobayashi@seaj.or.jp

TEL 03-3261-8261



Semiconductor Equipment Association of Japan

3,Rokubancho
Chiyoda-ku,Tokyo,Japan
Web <http://www.seaj.or.jp>

January 2019 Billings (Express Report)

Japan-based Semiconductor Manufacturing Equipment

Note : All data is based on three month average numbers.

Mark your calendars. **The February Report SEAJ's Web site update** is scheduled on **19th March** approximately 4:00P.M.Japan Time. Up dates are subject to change.

Japanese Semiconductor Equipment Industry Posts **January 2019 Billings of ¥164,993 million**

Tokyo Japan, **February 20th, 2019** JAPAN-based manufacturers of semiconductor equipment posted **¥164,993 million** in billings in **January 2019** (three-month average basis) published today by SEAJ.

The billings figure is **1.8 percent down** the final **December 2018** level of **¥168,098 million** and **3.3 percent up** the **January 2018** billings level of **¥ 159,771 million**.

The SEAJ billings are three-month moving average billings for the Japanese semiconductor equipment industry. Billings figures are in millions of Japanese ¥.

	Billings (Three-month avg.)	Month-Over-Month	Year-Over-Year
August 2018	181,450	-3.9%	11.9%
September 2018	214,089	18.0%	34.7%
October 2018	200,113	-6.5%	29.5%
November 2018	204,672	2.3%	33.4%
December 2018(final)	168,098	-17.9%	8.1%
January 2019(prim)	164,993	-1.8%	3.3%

SEAJ can assume no responsibility for the accuracy of the underlying data.

The data are contained in a monthly Billings published by SEAJ that tracks billings worldwide of JAPAN-based manufacturers of equipment used to manufacture semiconductor devices, not billings of the chips themselves.

SEMI is released North American Semiconductor Manufacturing Equipment Billings Report on Website.

<http://www.semi.org/en/MarketInfo/billings>

CONTACT : Akihide Kobayashi General Manager of Public Relations Department SEAJ

Web <http://www.seaj.or.jp> E-mail akobayashi@seaj.or.jp